

L Number	Hits	Search Text	DB	Time stamp
1	1	("6353267").PN.	USPAT	2002/06/30 00:11
2	1	("5989982").PN.	USPAT	2002/06/30 00:22
3	2	((5994783) or (6228681)).PN.	USPAT	2002/06/30 01:12
4	30128	device and (post or column or pillar) and (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 01:13
5	28848	(device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:19
6	4679	((device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 01:15
7	566	((device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)) and (pad with (post or column or pillar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 01:30
8	1	("6191493").PN.	USPAT	2002/06/30 01:59
9	1	6191493.URPN.	USPAT	2002/06/30 01:46
10	19	("4472730"   "5093281"   "5128746"   "5139969"   "5171716"   "5205036"   "5237013"   "5244838"   "5304460"   "5304512"   "5321303"   "5331235"   "5371044"   "5373190"   "5427938"   "5438478"   "5474958"   "6007357"   "6014318").PN.	USPAT	2002/06/30 01:47
11	1154	257/786.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:00
12	1087	257/786.cccls. and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:09
13	1045	257/786.cccls. and (@ad<20000427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:01
14	48	(257/786.cccls. and (@ad<20010427)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:10
15	372	257/620.cccls. and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:09
16	7	(257/620.cccls. and (@ad<20010427)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:52
17	8	438/462.cccls. and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/30 02:16

18	11	438/460.ccls. and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:16
19	21	438/113.ccls. and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:18
20	852	((center or middle) with (pad or trace or electrode)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:19
21	797	((center or middle) with (pad or trace or electrode)) and ball and (pillar or column or post)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
22	628	((((center or middle) with (pad or trace or electrode)) and ball and (pillar or column or post)) and (@ad<20010427)) and (device or chip or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
23	32051	("6191493").PN. (step or stepped) with (molding or mold or encapsulant or rein)	USPAT	2002/06/30 02:51
24			USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:52
25	811	((step or stepped) with (molding or mold or encapsulant or rein)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
26	766	((step or stepped) with (molding or mold or encapsulant or rein)) and ball and (pillar or column or post)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
27	494	((((step or stepped) with (molding or mold or encapsulant or rein)) and ball and (pillar or column or post)) and (@ad<20010427)) and (device or chip or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 03:05
28	2306	(dielectric or insulating or insulation) near polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 03:06
29	382	((dielectric or insulating or insulation) near polyimide) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 03:07

L Number	Hits	Search Text	DB	Time stamp
1	899	257/787.cccls.	USPAT	2002/06/30 13:43
2	810	257/787.cccls. and (@ad<20000423)	USPAT	2002/06/30 14:22
3	0	(stepped adj shape) near encapsulant	USPAT	2002/06/30 14:10
4	0	(stepped adj shape) with encapsulant	USPAT	2002/06/30 14:09
5	2	(stepped adj shape) near (encapsulant or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:13
6	0	(stepped adj shape) with encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:16
7	1	("6351030").PN.	USPAT	2002/06/30 14:21
8	45	(remove or cut) near encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:25
9	36	((remove or cut) near encapsulant) and (@ad<20000428)	USPAT	2002/06/30 14:26
10	273	(remove or cut) with (encapsulant or (moldong adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:25
11	192	((remove or cut) with (encapsulant or (moldong adj resin))) and (@ad<20000428)	USPAT	2002/06/30 14:26